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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

INVENTOR: Edmund D. Blackshear)

SERIAL NO.: 10/719,334)

FILING DATE: November 21, 2003)

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FOR: OVERLAP STACKING OF CENTER BUS BONDED MEMORY CHIPS FOR
DOUBLE DENSITY AND METHOD OF MANUFACTURING THE SAME

CHANGE OF CORRESPONDENCE ADDRESS FOR ALL PURPOSES

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Commissioner for Patents
P.O. Box 1450
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Dear Sir:

Pursuant to 37 CFR §1.33, please change the correspondence address, (Customer No. 32074), for all purposes for the above identified patent application and resulting patent to:

**INTERNATIONAL BUSINESS MACHINES CORPORATION
Intellectual Property Law/Zip 482
2070 Route 52
Hopewell Junction, New York 12533-6531**

Respectfully submitted,

Robert Curcio
Reg. No. 44,638